

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING

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Attn: MAIL STOP ISSUE FEE

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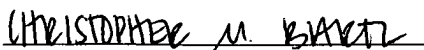
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